

Product / Package Information

Package	WLCSP
Body Size	
I/O Count	6
Terminal Finish	SnAgCu
MS Number	MS011055B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.37 E-04	100.00	1000000	7.85	78506

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.12E-04	95.50	955000	29.35	293466
Tin & its alloys	Silver	7440-22-4	2.14E-05	4.00	40000	1.23	12292
Tin & its alloys	Copper	7440-50-8	2.68E-06	0.50	5000	0.154	1536
Subtotal			5.36E-04	100.00	1000000	30.73	307294

UBM

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.60 E-05	89.95	899492	3.21	32117
Nickel & its alloys	Nickel	7440-02-0	5.05 E-06	8.10	81038	0.289	2894
Nickel & its alloys	Vanadium	7440-62-2	4.69E-07	0.75	7528	0.027	269
Other inorganic materials	Titanium	7440-32-6	7.44E-07	1.19	11942	0.043	426
Subtotal			6.23 E-05	100.00	1000000	3.57	35706

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	6.58 E-04	67.95	679500	37.70	376991
Other organic materials	Tetraethylene Glycol Dimethacrylate	109-17-1	1.41 E-04	14.56	145600	8.078	80780
Other organic materials	Trifluoroacetic Anhydride	407-25-0	5.64 E-05	5.83	58300	3.235	32345
Other organic materials	4,4'-Oxydiphthalic Anhydride	1823-59-2	5.64 E-05	5.83	58300	3.235	32345
Other organic materials	2-Hydroxyethyl Methacrylate	868-77-9	5.64 E-05	5.83	58300	3.235	32345
Subtotal			9.68E-04	100.0	1000000	55.48	554806

Backside Coating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	Proprietary	1.76 E-05	42.68	426800	1.01	10110
Thermoplastic	Epoxy Resin	Proprietary	1.16 E-05	28.05	280500	0.66	6644
Thermoplastic	Acrylic polymer	Proprietary	1.16 E-05	28.05	280500	0.66	6644
Other organic materials	Carbon black	Proprietary	5.04 E-07	1.22	12200	0.03	289
Subtotal			4.13 E-05	100.0	1000000	2.37	23688

Package Totals	Weight (g)	Percentage (%)	PPM
	1.74 E-03	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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